

Title (en)

COMPOSITION AND CORRESPONDING METHOD FOR THE ELECTRODEPOSITION OF INDIUM COMPOSITES

Title (de)

ZUSAMMENSETZUNG UND ENTSPRECHENDES VERFAHREN ZUR GALVANISCHEN ABSCHIEDUNG VON INDIUMVERBUNDWERKSTOFFEN

Title (fr)

COMPOSITION ET PROCÉDÉ CORRESPONDANT POUR L'ÉLECTRODEPOSITION DE COMPOSITES D'INDIUM

Publication

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Application

EP 08162974 A 20080826

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Abstract (en)

Electrochemically deposited indium composites are disclosed. The indium composites include indium metal or an alloy of indium with one or more ceramic materials. The indium composites have high bulk thermal conductivities. Articles containing the indium composites also are disclosed.

IPC 8 full level

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Citation (applicant)

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